Booth No. **8.1B41-4**

TNHtek Co., Ltd.

Year Established	2022	Type of Business	Manufacturing
Website	www.tnhtek.kr	Main Export Countries	
SNS			
Main Customer	Domestic Customers	International Customers	
	Samsung Mobile for samples stage		
The Person In Charge	Name	Department	Position
	Yoon-Seok Cha (Lucas)	Sales	Vice-president
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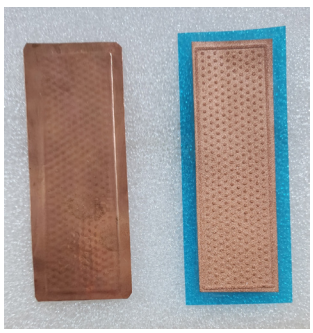
Company Description

TNHTek specializes in next-generation thermal components like VC, TVC, HTS, and Hi-Solation, a shielding material against ESD, EOS, and EMI. Our thermal solutions enhance device performance and lifespan. Integrated wick technology reduces costs, while Hi-Solation shields over 20kV electromagnetic waves, offering cost advantages over on-chip solutions.

Product

Vapor Chamber

Function and Usage : A vapor chamber is a high-performance heat spreading device used in electronics to manage thermal loads. It works by transferring heat through the evaporation and condensation of a working fluid inside a sealed chamber. This ensures uniform heat distribution, reduces hotspots, and enhances cooling efficiency. Vapor chambers are widely used in smartphones, laptops, servers, and high-power devices to improve performance, reliability, and device lifespan under demanding thermal conditions.

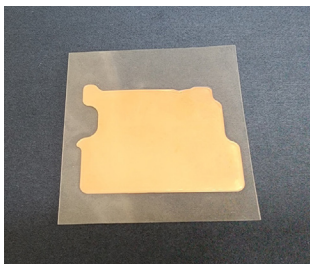


Marketing and Selling Points : Our product aims to appeal to the market with the following advantages :

1) Integration of the wick inside the chamber — capillary + pillar
2) Reduction of manufacturing costs through a streamlined process
3) Realization of an eco-friendly, low-carbon process through carbon reduction
4) Applicable for PCs, TVs, and electric vehicles
5) Achieves a 30% cost reduction effect

Thermal Vacuum Chamber

Function and Usage : TVC, a thermal vacuum chamber, is designed to replace ultrathin vapor chamber alternatives by stacking thin graphite layers inside the chamber. While direct performance comparison is not possible due to the lack of such products, TVC offers superior thermal conductivity, scalability to larger sizes, and serves as an advanced heat dissipation solution for various applications.



Marketing and Selling Points :

1) World's first ultra-thin design under 200 μ m
 - innovative lightweight and compact design
2) Scalable to larger sizes
 - to various sizes, suitable for large-scale
3) High thermal performance despite Ultra-thin design
4) Ideal for mobile applications
5) Cost competitiveness
6) Eco-friendly manufacturing process
 - to carbon reduction
7) Applicable models
 -.Suitable for mobile devices, laptops, electric vehicles, high-performance servers,